



17-19, December 2026

Organized by



**RV College of
Engineering®**

**RV College of Engineering
Bengaluru, Karnataka, India**

Technical Sponsors



About the College

RV College of Engineering- Established in 1963 with three engineering branches namely Civil, Mechanical and Electrical, today RVCE offers 12 Under Graduate Engineering programmes, 16 Master Degree programmes and Doctoral Studies. Located 13 km from the heart of Bangalore City – the Silicon Valley of India, on Mysore Road. Sprawling campus spread over an area of 16.85 acres(16.43 guntas) set in sylvan surroundings. Provides an ideal ambience to stimulate the teaching-learning process, helping in bringing out skilled and disciplined Engineers. Rated one amongst the top ten self-financing Engineering Institutions in the country. Current annual student intake for Undergraduate Programmes & Post Graduate Programmes in Engineering is in excess of 1200. Highly qualified and dedicated faculty. Utilizes its expertise in various disciplines to conduct Research and Development for Industry and Defense establishments in the country.

About the Conference

The International Conference on Emerging Applications of Material Science and Technology (ICEAMST 2026), scheduled to take place on 17-19, December 2026, at RV College of Engineering, Bengaluru, India, is set to be an exciting collaborative event in the dynamic landscape of material science and technology. This year, themed around "Innovations in Electronic Materials: Advancing Technology for a Sustainable Future," ICEAMST 2026 aims to be an interdisciplinary platform for researchers, scientists, and engineers in the field of material science and engineering. This conference intends to enable an interdisciplinary research collaboration, providing insights into state-of-the-art developments in nano electronics, sustainable technologies, and the multifunctionality, reliability, and scalability of electronic materials. ICEAMST 2026 not only showcases the latest research findings but also fosters a collaborative environment, encouraging participants to share the research discoveries and advancements.

SUBMISSION

All papers must be novel and not simultaneously submitted to another conference/journal. All the manuscripts should be submitted via conference Email iceamst@rvce.edu.in in DOCX (WORD)/PDF format as per the format. Maximum number of pages allowed will be 6-8. Authors should ensure that the similarity score of their research paper is not above 15%. Manuscripts having a similarity score more than 10% shall not be processed.

WEBSITE LINK

<https://iceamst.com/>

Venue

**RV College of Engineering RV Vidyaniketan Post, Mysore Road, Bengaluru,
Karnataka-560059, India**

CALL FOR PAPERS

Track 1: Advanced Electronic Materials and Electronics

- 2D and 3D materials for next-generation electronics
- Layered materials for flexible and transparent electronic devices
- Stretchable and biodegradable electronics
- High-performance dielectric and piezoelectric applications
- Transistors and memory architectures
- Advanced signal and imaging technologies
- Bio-inspired electronic systems
- Edge computing and AI-integrated embedded devices
- Quantum materials for future electronics
- MEMS and NEMS innovations
- Advanced satellite and deep-space communication materials
- 5G and 6G-ready electronic circuits and architectures
- High-speed photonic and optoelectronic systems
- Terahertz and sub-terahertz communication materials
- Nanoelectronic sensor applications

Track 2: Sustainable Materials and Communication Technologies

- Energy-harvesting materials for smart electronics
- Self-repairing and bio-degradable electronic components
- Circular economy and sustainable electronic waste management
- Next-gen VLSI and ULSI eco-friendly architectures
- High-efficiency RF and microwave materials
- Advanced remote sensing technologies
- AI-driven material design for green communications
- Smart grid innovations with sustainable materials
- Robotics and drone-based environmental monitoring
- Secure and reliable communication protocols
- Computational methods for sustainable material synthesis
- Terahertz communication materials
- AI-based misinformation detection in communication systems

Track 3: Materials for Control, Automation and Industry 4.0

- Intelligent materials for automation and robotics
- AI-integrated sensor networks for industrial automation
- Machine learning-driven adaptive control systems
- Bio-compatible smart coatings for automation
- Quantum-enhanced process control
- Advanced AI-driven robotic applications in agriculture
- Sustainable power electronics for electric mobility
- High-efficiency autonomous vehicle materials
- Smart materials for human-machine collaboration
- Digital twin and cyber-physical systems in Industry 4.0

Track 4: Materials for Networking and Computing

- Advanced photonic computing materials
- AI-powered security materials for quantum networks
- Future-proof materials for high-speed networking
- Emerging substrates for 6G and beyond
- Bio-inspired materials for secure information transfer
- Edge computing hardware innovations
- AI-driven networking topologies and architectures
- AR/VR-assisted networking material advancements
- Secure hardware-based cryptographic materials
- Impacts of advanced networking materials
- Low-latency materials for high-performance computing

Track 5: Applications of Material Science and Computing Technologies

- Materials for next-gen biomedical implants and sensors
- Hybrid material innovations for sustainable engineering
- Emerging trends in smart material synthesis
- AI-assisted material design and optimization
- LiDAR and hyperspectral imaging material applications
- High-speed computing materials for AI acceleration
- Novel bio-mimetic materials for medical applications
- AI-driven nano-material fabrication
- Augmented and virtual reality-based material applications
- Computational intelligence for material property prediction

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Indian Listener	8,000 INR	9,000 INR	10,000 INR
Foreign Authors	130 USD	150 USD	170 USD

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